

AMENDMENTS TO THE CLAIMS

Please amend Claim 5 of the Application as follows, without prejudice or disclaimer to continued examination on the merits; the status of all claims being as indicated:

Claims 1-4 (canceled)

Claim 5 (currently amended): Platinum temperature sensor comprising:

a ceramic substrate;

a platinum thin-film resistor applied to the ceramic substrate;

a ceramic cover layer; and

a connecting layer made of a glaze comprising a glass that is applied to the ceramic substrate in a frame-like shape in a border area surrounding the platinum thin-film resistor by means of which the ceramic cover layer is connected with the ceramic substrate in such a way that the platinum thin-film resistor is sealingly encapsulated with regard to the environment, wherein an interior portion of the connecting layer defines a void within which the platinum thin-film resistor is disposed, and wherein a portion of the ceramic cover layer coincident with the void defined by the interior portion of the connecting layer is disposed directly adjacent to the platinum thin-film resistor.

Claims 6-13 (canceled)

Claim 14 (previously presented): Platinum temperature sensor according to claim 5 wherein the ceramic substrate is made of Al_2O_3 .

Claim 15 (previously presented): Platinum temperature sensor according to claim 5 wherein the ceramic cover layer is made of Al_2O_3 .

Claim 16 (previously presented): Platinum temperature sensor according to claim 5 wherein a sealing cover is applied to the outer peripheral edges of the layer structure comprising the ceramic substrate, the connecting layer, and the ceramic cover layer.

Claim 17 (previously presented): Platinum temperature sensor according to claim 16 wherein the sealing cover is made of a glass.